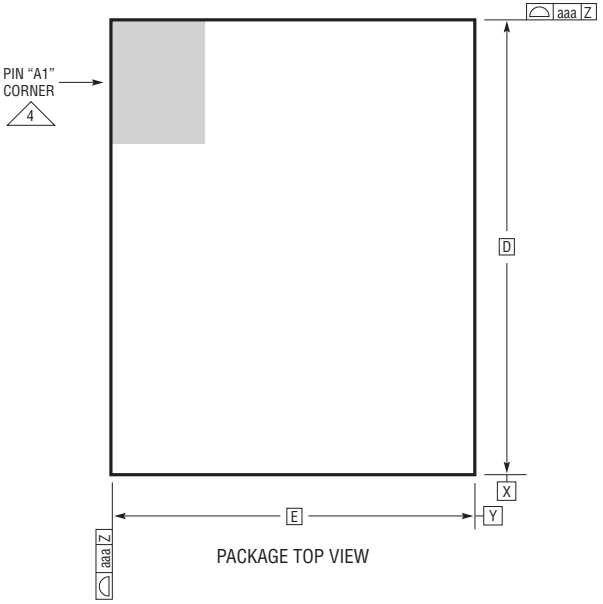
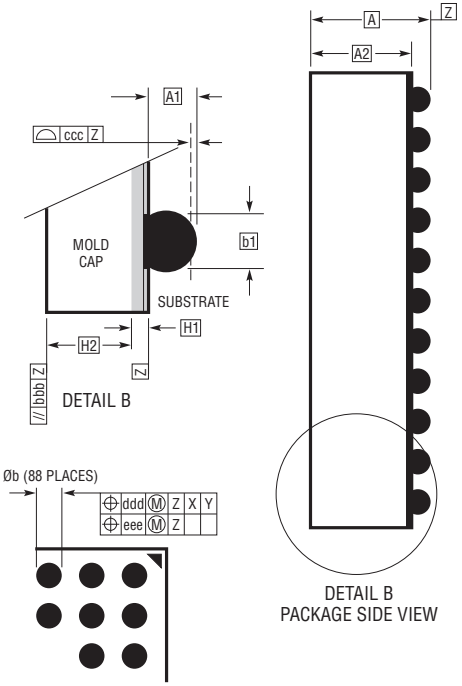
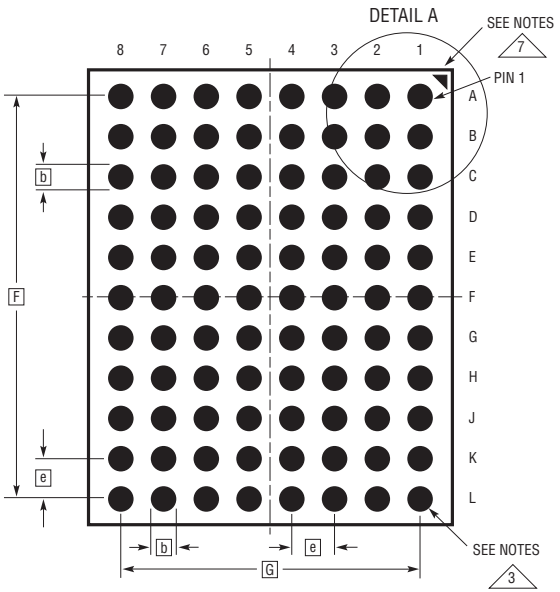
## BGA Package
## 88-Lead (11.25mm × 9mm × 3.32mm)
(Reference LTC DWG # 05-08-1535 Rev Ø)

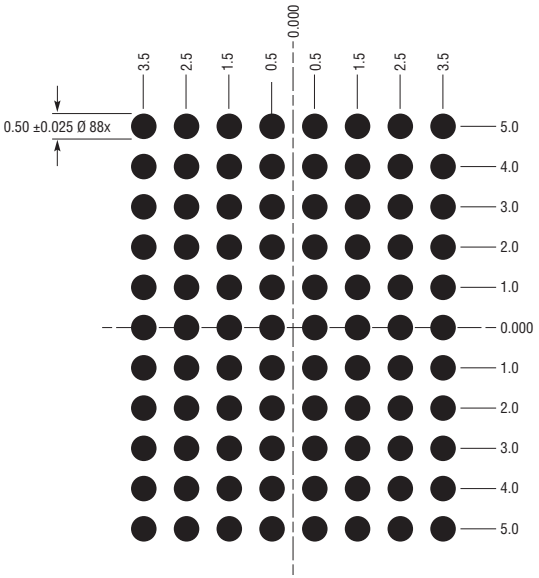


PACKAGE TOP VIEW



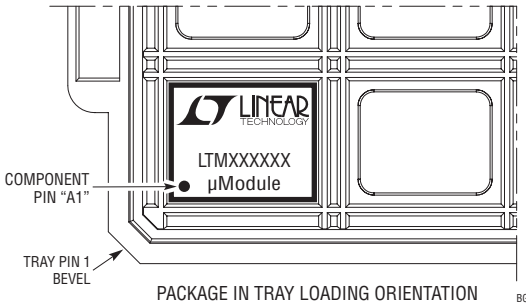
PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

| DIMENSIONS | | | | |
|---|---|---|---|---|
| SYMBOL | MIN | NOM | MAX | NOTES |
| A | 3.12 | 3.32 | 3.52 | |
| A1 | 0.40 | 0.50 | 0.60 | |
| A2 | 2.72 | 2.82 | 2.92 | |
| b | 0.50 | 0.60 | 0.70 | |
| b1 | 0.47 | 0.50 | 0.53 | |
| D | | 11.25 | | |
| E | | 9.00 | | |
| e | | 1.00 | | |
| F | | 10.00 | | |
| G | | 7.00 | | |
| H1 | 0.27 | 0.32 | 0.37 | |
| H2 | 2.45 | 2.50 | 2.55 | |
| aaa | | | 0.15 | |
| bbb | | | 0.10 | |
| ccc | | | 0.20 | |
| ddd | | | 0.25 | |
| eee | | | 0.10 | |
| TOTAL NUMBER OF BALLS: 88 | | | | |

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 88 0316 REV Ø